

IN THE CLAIMS

Please amend the claims as follows:

1 – 29. (Cancelled)

30. (Currently Amended) A drive electronics for driving an optoelectronic device with a matrix of picture elements, comprising:

a drive circuit, wherein the drive circuit comprises input terminals and output terminals, wherein the drive circuit is configured for receiving external signals and for providing modified signals for the matrix of picture elements during normal operation and during test mode;

a first arrangement of contact areas connected with the input terminals of the drive circuit, wherein the first arrangement of contact areas serves for picture generation during normal operation; and

a second arrangement of contact areas connected with the input terminals of the drive circuit directly or via another component, wherein the contact areas of the second arrangement of contact areas are larger than the contact areas of the first arrangement of contact areas, and the second arrangement of contact areas serves for pattern generation during test mode.

31. (Previously Presented) The drive electronics according to claim 30, wherein:

the number of input terminals of the drive circuit by which the drive circuit is connected with the second arrangement of contact areas is at most 5% of the number of output terminals of the drive circuit by which the drive circuit is connected with the control lines of the matrix of picture elements.

32. (Cancelled)

33. (Withdrawn) The drive electronics according to claim 30, wherein:

the second arrangement of contact areas is connected with the drive circuit via the first arrangement of contact areas.

34. (Withdrawn) The drive electronics according to claim 33, wherein:
the second arrangement of contact areas is connected with the drive circuit via the first arrangement of contact areas by means of switching elements or components.

35. (Withdrawn) The drive electronics according to claim 33, wherein:
the second arrangement of contact areas is directly connected with the drive circuit via the first arrangement of contact areas.

36. (Withdrawn) The drive electronics according to claim 30, wherein:
the second arrangement of contact areas is connected with the drive circuit via a test electronics.

37. (Previously Presented) The drive electronics according to claim 30, wherein:
the second arrangement of contact areas is directly connected with the drive circuit.

38. (Withdrawn) The drive electronics according to claim 37, wherein:
test circuits are integrated into the drive circuit.

39. (Previously Presented) The drive electronics according to claim 30, wherein:
the first arrangement of contact areas comprises one or more first pads, the second arrangement of contact areas comprises one or more second pads, and the number of second pads of the second arrangement of contact areas is at most 90% of the number of first pads of the first arrangement of contact areas.

40. (Previously Presented) The drive electronics according to claim 30, wherein:
the first arrangement of contact areas comprises one or more first pads, the second arrangement of contact areas comprises one or more second pads, and the second pads

of the second arrangement of contact areas are larger than the first pads of the first arrangement of contact areas.

41. (Previously Presented) The drive electronics according to claim 30, wherein:
the second arrangement of contact areas comprises one or more second pads, and
the second pads of the second arrangement of contact areas have a dimension of at least 100 μm .

42. (Currently Amended) An arrangement of test contact areas for an optoelectronic device comprising a matrix of picture elements, comprising:

at least one pad;

at least one connection of the at least one pad with a drive circuit directly or via another component, wherein the drive circuit is provided with signals via an arrangement of operational contact areas during normal operation, the drive circuit is configured for receiving external signals and for providing modified signals for the matrix of picture elements during normal operation and during test mode[[:]], wherein the arrangement of test contact areas are larger than the arrangement of operational contact areas, and the arrangement of test contact areas is configured for providing signals for generating a test pattern during test mode.

43. (Previously Presented) The arrangement according to claim 42, wherein:
the drive circuit has input terminals and output terminals, and wherein the at least one connection is connected with at least one of the input terminals.

44. (Previously Presented) The arrangement according to claim 42, wherein:
the at least one pad of the arrangement of test contact areas has a dimension of at least 100 μm .

45. (Previously Presented) The arrangement according to claim 42, wherein:

the number of pads of the arrangement of test contact areas is at most 90% of the number of pads of the arrangement of operational contact areas.

46. (Withdrawn) The arrangement according to claim 42, wherein:
the arrangement of test contact areas is connected with the drive circuit via the arrangement of operational contact areas.
47. (Withdrawn) The arrangement according to claim 42, wherein:
the arrangement of test contact areas is connected with the drive circuit via a test electronics.
48. (Previously Presented) The arrangement according to claim 42, wherein:
the arrangement of test contact areas is directly connected with the drive circuit.
49. (Previously Presented) An optoelectronic device, comprising:
a matrix of picture elements; and
a drive electronics according to claim 30.
50. (Currently Amended) A method for testing an optoelectronic device, comprising:
a) making contact between an external control and an arrangement of test contact areas which are larger than operational contact areas;
b) providing an input terminal of a drive circuit directly or via another component with input signals via the arrangement of test contact areas to generate a test pattern on a matrix of picture elements, wherein the drive circuit is provided with signals for picture generation during operation via the operational contact areas connected to the input terminal of the drive circuit, the drive circuit is configured for receiving external signals and for providing modified signals for the matrix of picture elements during normal operation and during test mode; and
c) testing the picture elements of the matrix of picture elements.

51. (Previously Presented) The testing method according to claim 50, wherein:
the input signals generate a periodic test pattern.
52. (Previously Presented) The testing method according to claim 50, wherein:
the input signals generate a vertically, horizontally or diagonally periodic test pattern.
53. (Previously Presented) The testing method according to claim 50, wherein:
the picture elements are tested with a beam of charged particles or laser radiation.
54. (Previously Presented) The testing method according to claim 50, comprising the further step of:
a vacuum is generated in the vicinity of the optoelectronic device to be tested.
55. (Previously Presented) The testing method according to claim 50, wherein step c) comprises the following steps:
c1) testing the picture elements in a portion of the matrix of picture elements;
c2) shifting the optoelectronic device; and
c3) testing the picture elements in a further portion of the matrix of picture elements.
56. (Currently Amended) A method for manufacturing a drive electronics of an optoelectronic device having a matrix of picture elements, comprising:
a) providing a drive circuit configured for receiving external signals and for providing modified signals for the matrix of picture elements during normal operation and during test mode;
b) connecting control lines of the matrix of picture elements with output terminals of the drive circuit;
c) providing a first arrangement of contact areas, wherein the first arrangement of contact areas provides signals to the drive circuit during operation mode;

d) connecting the first arrangement of contact areas with input terminals of the drive circuit;

e) providing a second arrangement of contact areas, said second arrangement of contact areas being larger than the contact areas of said first arrangement of contact areas, wherein said second arrangement of contact areas serve for pattern generation during test mode; and

f) connecting the second arrangement of contact areas with input terminals of the drive circuit directly or via another component.

57. (Previously Presented) An optoelectronic device, which has been tested by a testing method according to claim 50 or by an apparatus according to claim 30.

58. (Previously Presented) An optoelectronic device according to claim 49, wherein at least parts of the second arrangement of contact areas are removed.